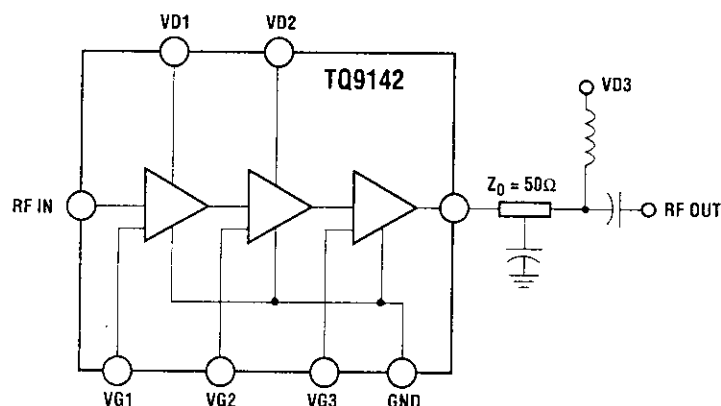




SEMICONDUCTOR, INC.



The TQ9142B is a highly efficient 3-stage power amplifier developed for handsets and portable terminals operating in the AMPS cellular band (824-849 MHz). The part is designed to require minimal external circuitry for matching or bias, simplifying design and keeping board space and cost to a minimum. Access to each stage's gate and drain voltages is provided for maximum flexibility in selection of output power control method, making output power vs. efficiency tradeoffs, or for implementing alternative biasing schemes. The amplifier is packaged in a space-efficient SOIC-16 plastic package with specially modified central thermal tabs. These tabs provide reliable operation for the 1.4 Watt power output.

Electrical Specifications

Test Conditions: $V_{DD} = +4.8 \text{ V}$, $V_{GG} = -3.5 \text{ V}$, $T_A = 25^\circ \text{C}$, $P_{IN} = 0 \text{ dBm}$

Parameter ⁽¹⁾	Min	Typ	Max	Units
Frequency Range	824		849	MHz
Output Power	30.0	31.0		dBm
Efficiency	55	60		%
Input Return Loss		10		dB
Supply Voltage		4.8		V

1. Min/max values listed here are 100% production tested.

TQ9142B

High-Efficiency 3-Stage AMPS Power Amplifier IC

Features

- 60% drain efficiency
- +31.0 dBm power output @ 4.8 V
- 4.8 V to 6.0 V battery operation
- SO-16 package
- 50-Ω matched input
- Monolithic construction

Applications

- Analog cellular handsets
- CDPD terminals

TQ9142B

Operating Range

Parameter	Conditions	Min	Typ	Max	Units
Frequency Range	Matched for cellular band	824		849	MHz
Supply Voltage (V_{DD})	Output power varies w/supply voltage	2.7	5.0	7.0	V
Temperature	Measured at case	-40	25	110	°C

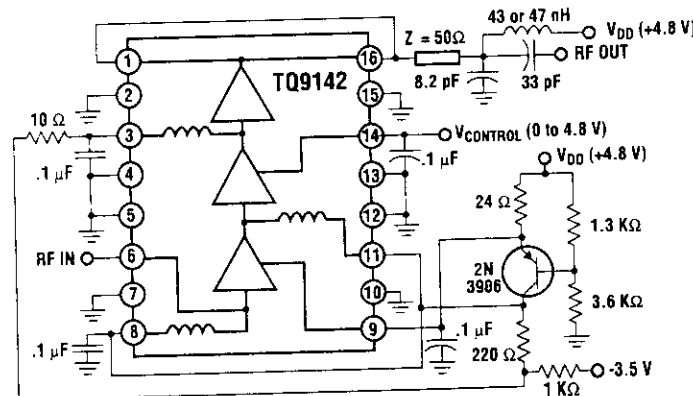
Electrical Characteristics

Test Conditions: $V_{DD} = +4.8$ V, $V_{GG} = -3.5$ V, $P_{IN} = 0$ dBm, B.W. = 30 KHz

Parameter	Conditions	Min	Typ	Max	Units
Output Power		30.0	31.0		dBm
Efficiency		55	60		%
2nd Harmonic			-35		dBc
3rd Harmonic			-45		dBc
Input Return Loss			10		dB
Power Control Range			25		dB
Spurious Levels and Stability ⁽¹⁾	$P_{IN} = -40$ to $+0$ dBm		-80		dBc
Rx Band Noise ⁽²⁾			-88		dBm
Gain (small signal)	$P_{IN} = -10$ dBm		40		dB
Negative Supply Current			2	5	mA
Ruggedness ⁽³⁾		No Degradation			

- Notes: 1. Load VSWR set to 7:1 and the angle is varied 360°. All spurious outputs will be less than -80 dBc. No large-signal oscillations permitted.
 2. Noise power is measured in 30 KHz bandwidth at the transmit frequency plus 45 MHz.
 3. Burnout testing. Load set to 50 ohms, output power is measured at nominal test conditions. Load VSWR set to 10:1 and the angle varied 360° over 60 seconds. Load set to 50 ohms, output power is measured again and compared with the first measurement to check for no degradation from first measurement.

Test Circuit



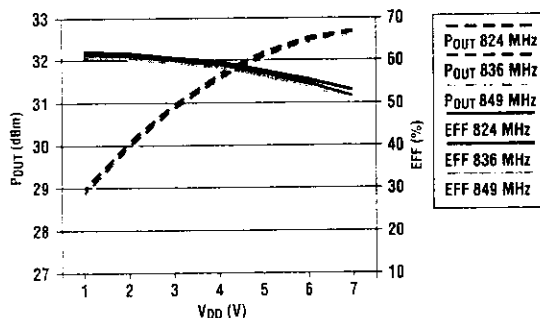
TQ9142B

Bias Circuit Description

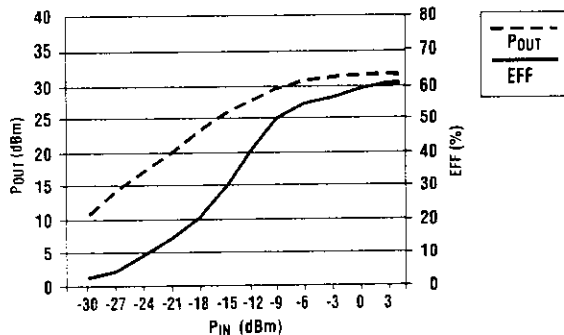
The TQ9142B is tested with the bias stabilization circuit shown in the test circuit schematic above. This circuit accurately sets the bias point for the power amplifier and provides low quiescent current and excellent efficiency at all operating voltages and output powers. Output power may be controlled by varying the supply voltage marked V_{CONTROL} . TriQuint recommends this circuit be incorporated into designs to provide the most predictable performance and the most robust performance in high-volume applications. The PNP transistor may be a 2N3906 or equivalent. A small footprint, dual PNP transistor such as the Rohm UMT1N, may also be used. The second PNP can be connected as a diode to temperature compensate the bias circuit.

Typical Performance – Tuned for V_{DD} (nom) = 4.8 V

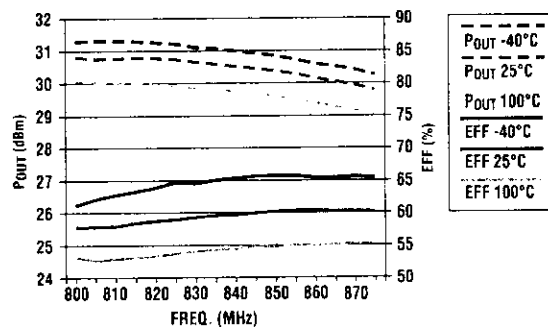
Output Power & Efficiency vs. V_{DD} vs. Frequency



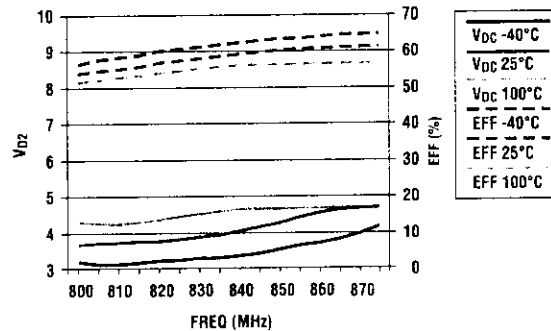
Output Power & Efficiency vs. Input Power @ 836 MHz



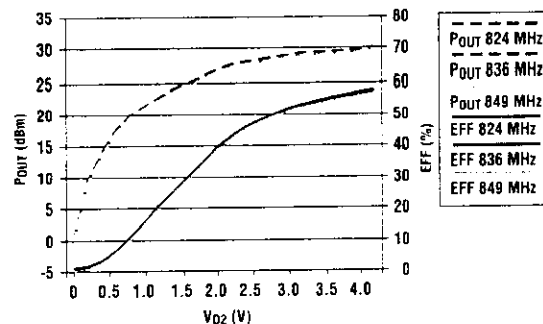
Output Power & Efficiency vs. Frequency vs. Temperature



V_{D2} & Efficiency vs. Frequency vs. Temperature at Constant P_{OUT} of 30 dBm



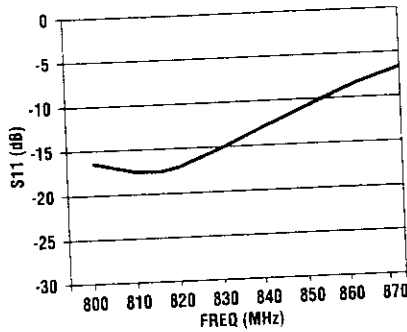
Output Power & Efficiency vs. V_{D2} vs. Frequency



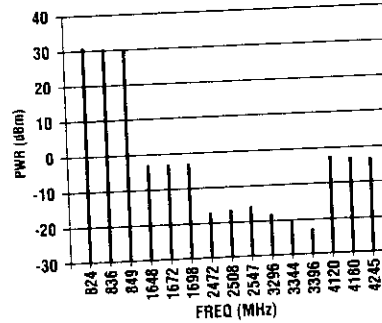
TQ9142B

Typical Performance — Tuned for $V_{DD} (nom) = 4.8 V$

S_{11} vs. Frequency

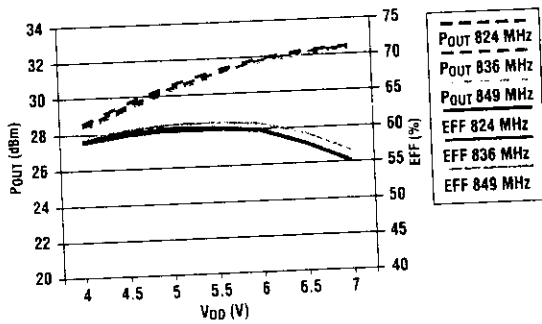


Fundamental & Harmonics vs. Frequency @ $T = 25^{\circ}C$

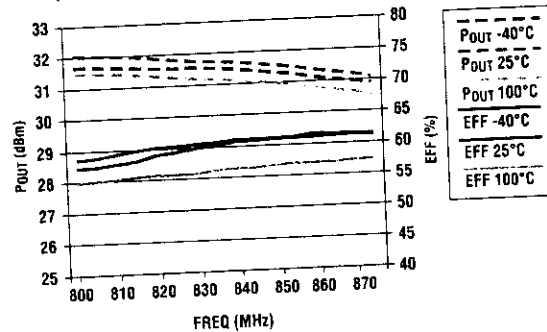


Typical Performance — Tuned for $V_{DD} (nom) = 5.8 V$

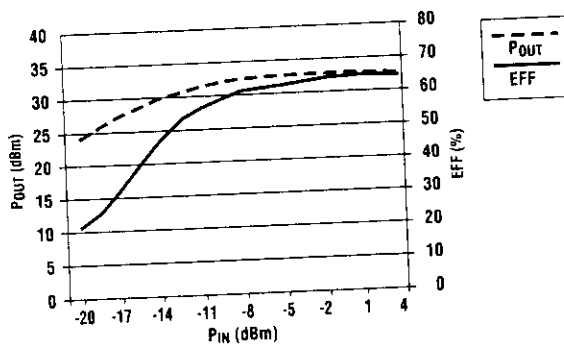
Output Power & Efficiency vs. V_{DD} vs. Frequency



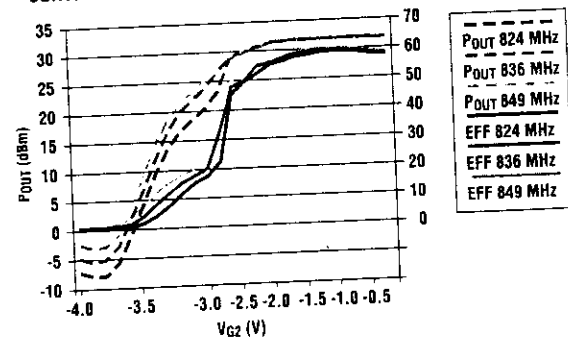
Output Power & Efficiency vs. Frequency vs. Temperature



Output Power & Efficiency vs. Input Power @ 836 MHz



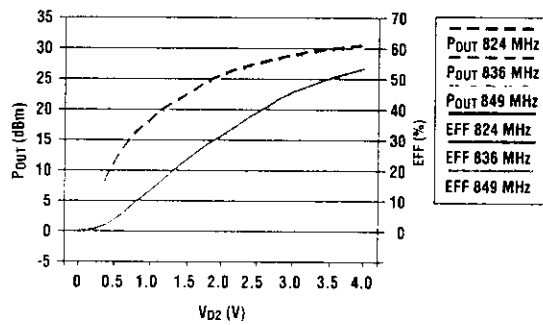
Output Power & Efficiency vs. $V_{CONTROL} (V_{G2})$ @ 836 MHz



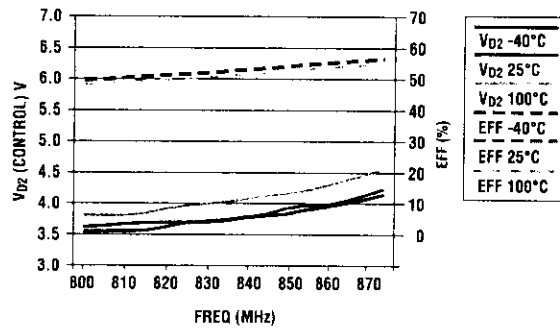
TQ9142B

Typical Performance — Tuned for $V_{DD}(\text{nom}) = 5.8 \text{ V}$

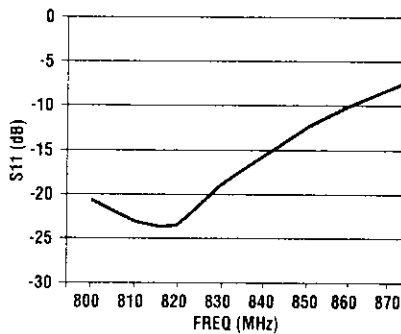
Power Output & Efficiency vs.
 V_{D2} vs. Frequency



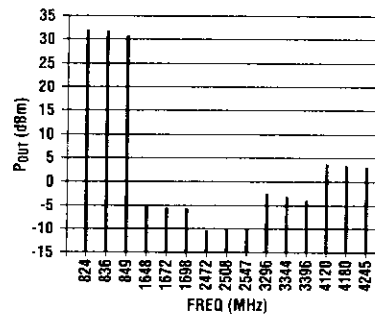
V_{D2} & Efficiency vs.
Temperature at Constant P_{OUT} of 30 dBm



S11 vs. Frequency vs. Temperature



Fundamental & Harmonics vs.
Frequency @ $T = 25^\circ\text{C}$



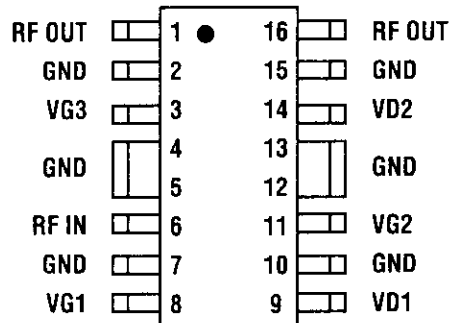
TQ9142B

Pin Descriptions

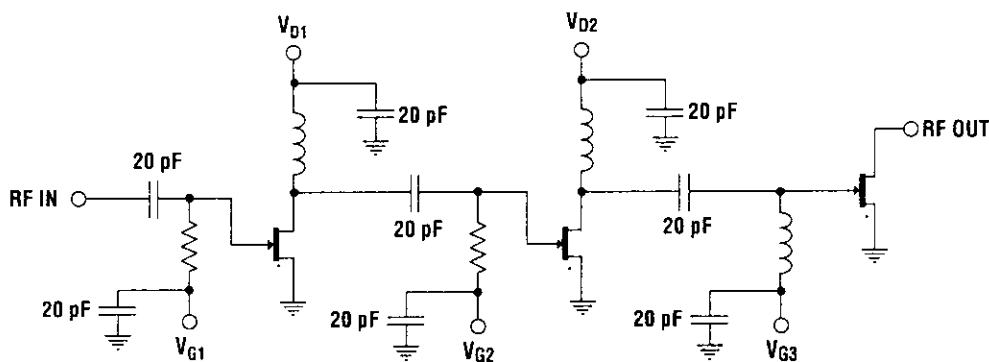
Pin Name	Pin #	Description
RF OUT	1, 16	Power amplifier output. Critical, but simple, matching circuit required.
V _{G3}	3	Output-stage gate voltage. Requires 51 Ω series resistor near device for stability. Local bypass cap required.
RF IN	6	Power amplifier input. Matched to 50 ohms. Internal DC block.
V _{G1}	8	First-stage gate voltage. Set V _{G1} = -1.5 V or use bias stabilization circuit.
V _{D1}	9	Input-stage supply voltage. Local bypass cap recommended. Use same voltage as V _{D3} or use bias stabilization circuit.
V _{G2}	11	Second-stage gate voltage. Local bypass cap required.
V _{D2}	14	Second-stage drain voltage. Local bypass cap required. Use same voltage as V _{D3} .
GND	(1)	Ground connection. It is very important to place multiple via holes immediately adjacent to the pins. Provides thermal path for heat dissipation and RF grounding

Note: 1. GND Pins are: 2, 4, 5, 7, 10, 12, 13, 15.

TQ9142B Pinout



TQ9142B — Simplified Schematic



General I

The TQ9142B is a power amplifier. It provides power at 60 dBm from 4.8 to 10 GHz. It has a minimal external output match allowing the efficiency.

The TQ9142B thermal tabs are used for analog cellular Data (CDPD) efficiency, high TQ9142B and tight time-to-

Gate Bias

A negative voltage is used for the Amplifier. The Amplifier is biased with a negative voltage with a series resistor. The Harris 7660 Supply Generator is used to produce a consistent output. The active bias is shown in the following table. The TQ9142B requires a negative gate bias for fabrication tolerance. The circuit overcomes extremely repetitive high-volume production.

Nominal Ga

TQ9142B

General Description

The TQ9142B is a gallium arsenide (GaAs) power FET amplifier. It has three stages of gain and features 1 Watt output power at 60% drain efficiency. It can operate at supply voltages from 4.8 to 6.0 V. The device is optimized for operation at frequencies from 824 to 849 MHz. The input is matched to 50 ohms and a simple output match and bypassing completes the minimal external circuitry required for normal operation. The output match and all gate and drain voltages are accessible, allowing the device to be optimized for V_{DD} , output power and efficiency.

The TQ9142B is packaged in a low-cost SOIC-16 package with thermal tabs. It is optimized for use as the transmit amplifier in analog cellular (AMPS) phones and for Cellular Digital Packet Data (CDPD) wide-area network (WAN) applications. Its high efficiency, high output power and ease of use make the TQ9142B an excellent solution for RF system designers with tight time-to-market and cost requirements.

Gate Biasing

A negative voltage is required to bias the TQ9142B Power Amplifier properly. This is usually generated from the battery voltage with a commercially available charge pump IC, such as the Harris 7660 or one of the Maxim 850 series Negative Supply Generator ICs. A simple resistive voltage divider can be used to produce the gate voltages for each stage, but the most consistent operation of the amplifier will be obtained by using the active bias circuit shown in the Test Circuit Schematic. The following table gives the approximate values of gate voltage for the TQ9142B at 4.8 Volts and 5.8 Volts. The specific values required for optimum performance vary slightly due to fabrication tolerances in FET pinch-off voltage. The active bias circuit overcomes these small variations and provides the extremely repeatable performance and operation needed for high-volume production.

Nominal Gate Bias Voltages

V_{DD}	4.8 V	5.8 V
V_{G1}	-1.3 V	-1.0 V
V_{G2}	-1.3 V	-1.4 V
V_{G3}	-1.8 V	-1.7 V

For a fixed output matching network, output power increases monotonically but gradually as gate voltage becomes more positive. Efficiency tends to rise to a peak, then to decrease with more positive gate voltage. See the P_{OUT} and efficiency vs. V_{G2} plots at each supply voltage.

Quiescent current, the total drain current flowing with no RF drive, also tends to increase with more positive gate voltage, and must be considered when selecting "optimum" gate bias voltages. The bias stabilization circuit used in the Test Circuit schematic does an excellent job of controlling quiescent current with variations in FET pinch-off voltage.

As with all GaAs power FETs, it is imperative to ensure that the gate bias is present before applying the drain voltage. Without the gate control, the drain current will rise to full I_{DSS} (~1.5 A) which is potentially destructive to power FETs which are designed to operate at 20% to 50% of I_{DSS} . This is usually more of a problem in a lab test environment, but it is a good idea to provide safeguards in the circuit design to minimize the risk that V_{DD} is applied for any significant length of time without V_{GG} applied.

Output Match

For maximum output power and efficiency, the output matching circuit for the TQ9142B is implemented off-chip with high-Q components. The use of external matching elements allows for some tradeoff adjustments to be made between supply voltage, output power and efficiency. It also allows some flexibility for optimizing the performance in different frequency ranges near the cellular band.

The desired output match impedance for optimum output power should have the impedance shown in the following table:

Optimum Power Match

V_{DD}	4.8 V	5.8 V
S11	.76 $\angle$ -179°	.73 $\angle$ +178°
Impedance	6.77-j.36 Ω	7.74+j.74 Ω

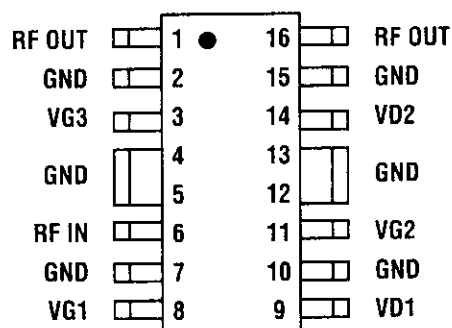
TQ9142B

Pin Descriptions

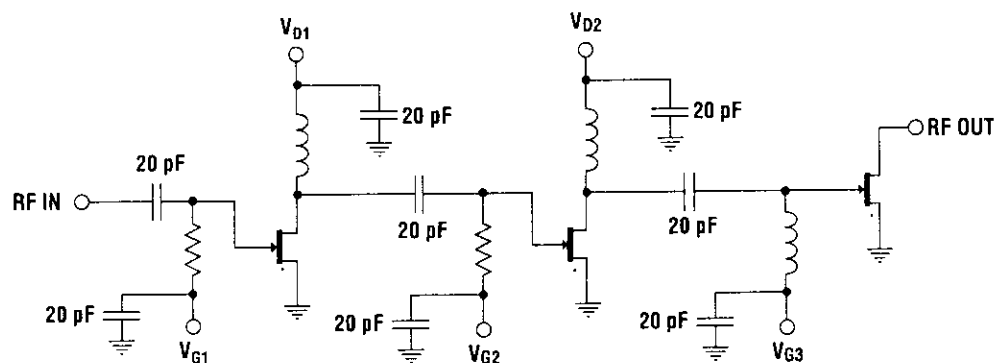
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V _{D2}	14	Second-stage drain voltage. Local bypass cap required. Use same voltage as V _{D3} .
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TQ9142B Pinout



TQ9142B — Simplified Schematic



TQ9142B

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V_{G1}	-1.3 V	-1.0 V
V_{G2}	-1.3 V	-1.4 V
V_{G3}	-1.8 V	-1.7 V

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Quiescent current, the total drain current flowing with no RF drive, also tends to increase with more positive gate voltage, and must be considered when selecting "optimum" gate bias voltages. The bias stabilization circuit used in the Test Circuit schematic does an excellent job of controlling quiescent current with variations in FET pinch-off voltage.

As with all GaAs power FETs, it is imperative to ensure that the gate bias is present before applying the drain voltage. Without the gate control, the drain current will rise to full I_{DSS} (~1.5 A) which is potentially destructive to power FETs which are designed to operate at 20% to 50% of I_{DSS} . This is usually more of a problem in a lab test environment, but it is a good idea to provide safeguards in the circuit design to minimize the risk that V_{DD} is applied for any significant length of time without V_{GG} applied.

Output Match

For maximum output power and efficiency, the output matching circuit for the TQ9142B is implemented off-chip with high-Q components. The use of external matching elements allows for some tradeoff adjustments to be made between supply voltage, output power and efficiency. It also allows some flexibility for optimizing the performance in different frequency ranges near the cellular band.

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Impedance	6.77-j.36 Ω	7.74+j.74 Ω

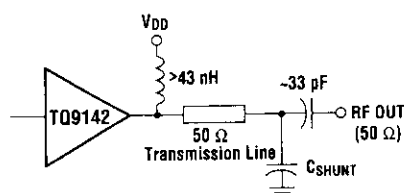
TQ9142B

The basic output network for the TQ9142B, (and for most GaAs FET power amplifiers), consists of a series inductor followed by a shunt capacitor. An RF choke for bringing the output stage supply voltage and a DC blocking capacitor are also needed.

The series inductance can be realized using a series transmission line or a combination of a series transmission line with a lumped element inductor. The transmission line characteristic impedance should be kept at 50 Ω .

The preferred topology for the output match is shown in the following figures for both the transmission line approach and the combination transmission line/lumped inductor approach.

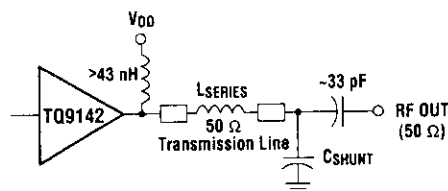
Output Match Topology - Transmission Line



Transmission Line Power Match

V_{DD}	4.8 V	5.8 V
Line Length	338 mils	365 mils
C_{SHUNT}	8.2 pF	6.8 pF

Output Match Topology - Lumped Inductance



Lumped Inductor Power Match

V_{DD}	4.8 V	5.8 V
L_{SERIES}	3.3 nH	3.9 nH
C_{SHUNT}	10 pF	8.2 pF

Please note that the value shown in the table for L_{SERIES} includes the equivalent inductance of any transmission line connecting the power amplifier to the inductor and any transmission line connecting the inductor to the shunt capacitor. Since these lines vary significantly from layout to layout, no attempt has been made here to estimate the approximate value of the physical lumped inductor. The closest standard values of lumped inductors that are lower than the required values are 2.2 nH and 1.8 nH. The connecting transmission lines must be kept fairly short since lumped inductors with values of less than 1.2 nH are not available in most sizes.

Power Control

The best method of power control for the TQ9142B is to vary V_{D2} . It is also possible to vary any of the gate voltages to achieve the same result, but the bias stabilization circuit shown in the Test Schematic works best if V_{D2} is the control voltage.

Power Down Function

To achieve minimum current leakage in standby mode, a silicon PMOS switching FET (PFET), such as the Siliconix Si9947, can be used in series with the supply voltage. When $V_{STANDBY}$ (active high) is applied to the gate of the PFET, the switch is turned off and only a few microamperes of current will flow. When $V_{STANDBY} = 0$, the switch is turned on and V_{DD} is applied to the power amplifier. Typically, the switch will drop the supply voltage by 0.1 to 0.2 V.

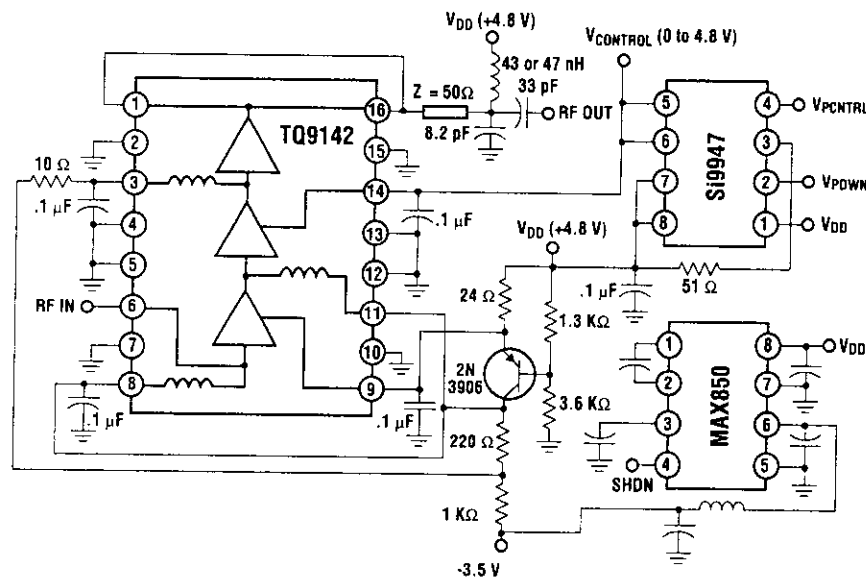
The turn-on and turn-off times for the TQ9142B using a PFET are 3 μ s and 13 μ s, respectively.

Single Supply Operation (Negative Voltage Generators)

Depletion-mode GaAs power FETs require a negative gate bias voltage (with respect to the grounded source). Several highly efficient negative supply generator ICs are available, such as the Maxim MAX850. The Typical Application Circuit figure includes the negative supply, the Silicon PFET and the bias circuit to illustrate a complete solution suitable for many cellular telephone designs.

TQ9142B

Typical Application Circuit



Absolute Maximum Ratings

Parameter	Min.	Typ.	Max.	Units
DC Power Supply			8.0	V
DC Gate Voltage	-5.0		-0.5	V
RF Input Power			+10	dBm
Storage Temperature	-55		+150	°C
Operating Temperature (case)	-40		+125	°C

ESD-sensitive device - Class 1